

## 2mm SIGNAL MALE

### MECHANICAL/CLIMATIC DATA

- Connection technique : compliant press-in, according to IEC 352-5  
diameter of plated through hole: 0.65÷0.8 mm
- Temperature range : -55 °C ÷ +125 °C

### MATERIALS

- Insulator : thermoplast glass fiber filled  
flammability according to UL94 V-0
- Contacts : copper alloy
- Contact plating : Ni + Au
- Press-fit zone plating : Ni + SnPb

### ELECTRIC DATA

- Current rating : 1.4 A at 20 °C  
1 A at 70 °C  
0.65 A at 100 °C
- Proof voltage : 1000 V<sub>rms</sub> (contact/contact)
- Insulation resistance : >5 x 10<sup>3</sup> MΩ
- Contact resistance : ≤25 mΩ

## 2mm POWER MALE

### MECHANICAL/CLIMATIC DATA

- Connection technique : compliant press-in, according to IEC 352-5  
diameter of plated through hole: 0.65±0.8 mm
- Temperature range : -55 °C ÷ +125 °C

### MATERIALS

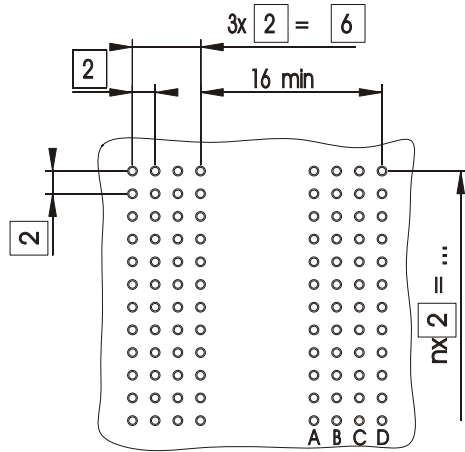
- Insulator : thermoplast glass fiber filled  
flammability according to UL94 V-0
- Contacts : copper alloy
- Contact plating : Ni + Au
- Press-fit zone plating : Ni + SnPb

### ELECTRIC DATA

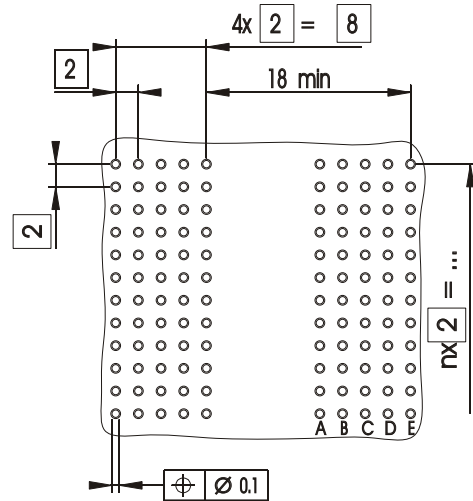
- Current rating : 4 A at 25 °C  
3 A at 70 °C
- Proof voltage : 1000 V<sub>rms</sub> (contact/contact)
- Insulation resistance : >5 x 10<sup>3</sup> MΩ
- Contact resistance : ≤25 mΩ

*Recommended printed board layout, component side*

*Styles BD-ED  
press-fit termination*



*Styles BE-EE  
press-fit termination*



## 2mm SIGNAL FEMALE

### MECHANICAL/CLIMATIC DATA

- Connection technique : compliant press-in, according to IEC 352-5  
diameter of plated through hole: 0.65÷0.8 mm
- Temperature range : -55 °C ÷ +125 °C
- Insertion force : 0.45 N max per individual contact
- Withdrawal force : 0.15 N min per individual contact

### MATERIALS

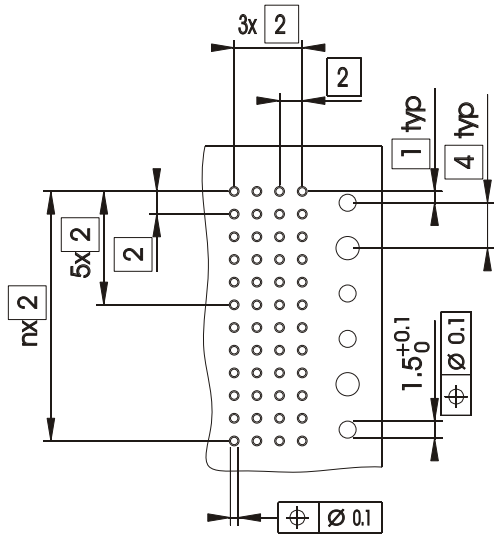
- Insulator : glass fiber-filled LCP  
flammability according to UL94 V-0
- Contacts : copper alloy
- Contact plating : Ni + Au
- Press-fit and solder zone plating : Ni + SnPb

### ELECTRIC DATA

- Current rating : 1.4 A at 20 °C  
1 A at 70 °C  
0.65 A at 100 °C
- Proof voltage : 1000 V<sub>rms</sub> (contact/contact)
- Insulation resistance : >5 x 10<sup>3</sup> MΩ
- Contact resistance : ≤25 mΩ

*Recommended printed board layout, component side*

*Styles PD  
press-fit and solder termination*



*Styles PE  
press-fit and solder termination*

